

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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**Spec No.: DS50-2008-0044** Effective Date: 08/17/2012

Revision: A

**LITE-ON DCC** 

**RELEASE** 

BNS-OD-FC001/A4

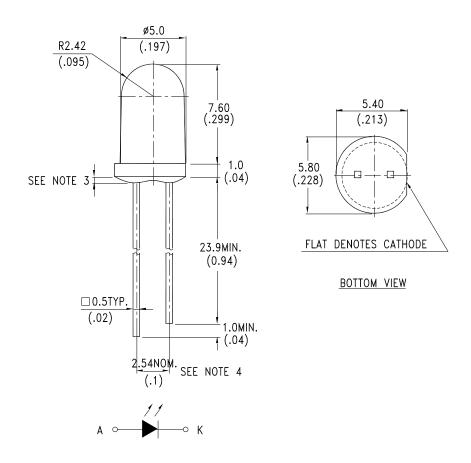
# LITEON LITE-ON TECHNOLOGY CORPORATION

Property of Lite-On Only

#### **FEATURES**

- \* HIGH SPEED
- \* HIGH POWER
- \* AVAILABLE FOR PULSE OPERATING
- \* CLEAR TRANSPARENT COLOR PACKAGE

#### PACKAGE DIMENSIONS



#### NOTES:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm 0.25$ mm(.010") unless otherwise noted.
- 3. Protruded resin under flange is 1.5mm(.059") max.
- 4. Lead spacing is measured where the leads emerge from the package.
- 5. Specifications are subject to change without notice.

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# LITEON LITE-ON TECHNOLOGY CORPORATION

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### ABSOLUTE MAXIMUM RATINGS AT TA=25°C

PARAMETER	MAXIMUM RATING	UNIT			
Power Dissipation	200	mW			
Peak Forward Current (300pps, $10 \mu$ s pulse)	1	A			
Continuous Forward Current	100	mA			
Reverse Voltage	5	V			
Operating Temperature Range	-40°C to + 85°C				
Storage Temperature Range	-40°C to + 85°C				
Lead Soldering Temperature [1.6mm(.063") From Body]	260°C for 6 Seconds				

### ELECTRICAL / OPTICAL CHARACTERISTICS AT TA=25°C

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITION
Aperture Radiant Incidence	Ee	1.3	1.7	-	mW/cm2	$I_F = 20 \text{mA}$
Radiant Intensity	IE	9.75	12.75	-	mW/sr	$I_F = 20 \text{mA}$
Radiant Intensity	IE	24	32	-	mW/sr	$I_F = 50 \text{mA}$
Peak Emission Wavelength	λР	-	850	-	nm	$I_F = 50 \text{mA}$
Spectral Line Half-Width	Δλ	-	40	-	nm	$I_F = 50 \text{mA}$
Forward Voltage	VF	-	1.49	1.80	V	$I_F = 50 \text{mA}$
Forward Voltage	VF	-	1.83	2.3	V	$I_F = 200 \text{mA}$
Reverse Voltage	$V_R$	5	-	-	V	$I_R = 10 \mu A$
Viewing Angle (See FIG.6)	2 \theta 1/2	-	50	-	deg.	$I_F = 20 \text{mA}$

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#### TYPICAL ELECTRICAL / OPTICAL CHARACTERISTICS CURVES

(25°C Ambient Temperature Unless Otherwise Noted)

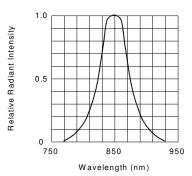


FIG.1 SPECTRAL DISTRIBUTION

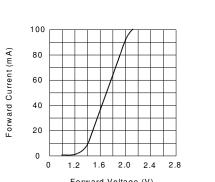


FIG.3 FORWARD CURRENT VS. FORWARD VOLTAGE

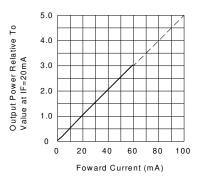


FIG.5 RELATIVE RADIANT INTENSITY VS. FORWARD CURRENT

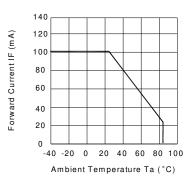


FIG.2 FORWARD CURRENT VS. AMBIENT TEMPERATURE

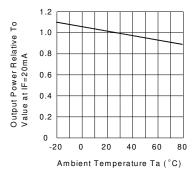


FIG.4 RELATIVE RADIANT INTENSITY VS. AMBIENT TEMPERATURE

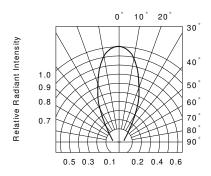


FIG.6 RADIATION DIAGRAM

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